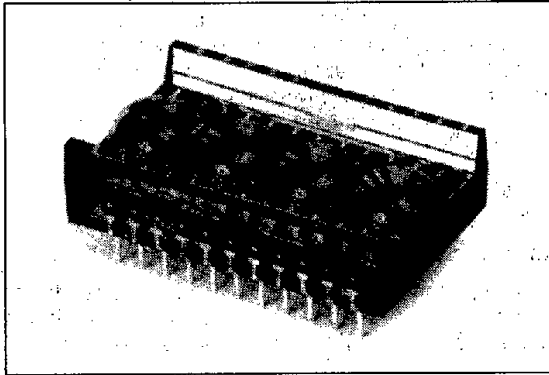


SIEMENS

DL3416

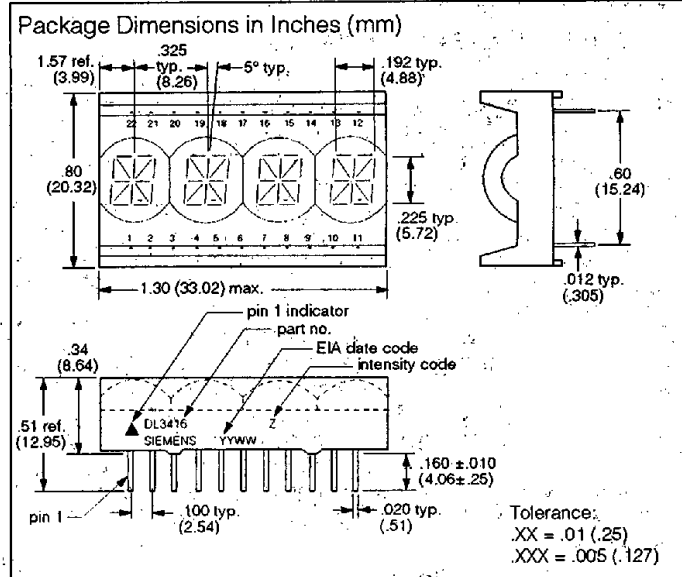
.225" Red, 4-Character 16 Segment Plus Decimal Alphanumeric Intelligent Display® With Memory/Decoder/Driver

Preliminary Data Sheet



FEATURES

- 0.225" x 0.192 Magnified Monolithic Character
- Wide Viewing Angle, X Axis $\pm 45^\circ$, Y Axis $\pm 55^\circ$
- Close Multi-line Spacing, 0.8" Centers
- Rugged Solid Plastic Encapsulated Package
- Fast Access Time, 110 ns at 25°C
- Full Size Size for Stationery Equipment
- Built- in Memory
- Built- in Character Generator
- Built- in Multiplex and LED Drive Circuitry
- Each Digit Independently Addressed
- Independent Cursor Function
- 17th Segment for Improved Punctuation Marks
- Memory Clear Function
- Display Blank Function for Blinking and Dimming
- End Stackable, 4 Character Package
- Intensity Coded for Display Uniformity
- Extended Operating Temperature Range:
-40°C to +85°C
- Wave Solderable
- 100% Burned in and Tested
- Superior ESD Immunity



DESCRIPTION

The DL3416 is a four digit display module with 16 segments plus a decimal and a built-in CMOS integrated circuit.

The integrated circuit contains memory, ASCII ROM decoder, multiplexing circuitry, and drivers. Data entry is asynchronous and can be random. A display system can be built using any number of DL3416s since each digit in any DL3416 can be addressed independently and will continue to display the character last stored until replaced by another.

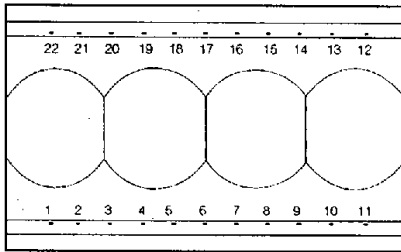
System interconnection is also straightforward. The least significant two address bits (A0 A1) are normally connected to the like named inputs of all DL3416s in the system. With four chip enables, four DL3416s (16 characters) can easily be interconnected without a decoder.

Alternately, one-of-n decoder ICs can be used to extend the address for large displays.

Data lines are connected to all DL3416s directly and in parallel, as is the write line (WR). The display will then behave as a write-only memory.

All products are 100% burned in and tested, then subjected to outgoing AQL's of 0.25% for brightness matching, visual alignment, and dimensions, 0.065% for electrical and functional.

TOP VIEW



Pin	Function	Pin	Function
1	CE1 Chip Enable	12	GND
2	CE2 Chip Enable	13	NC
3	CE3 Chip Enable	14	BL Blanking
4	CE4 Chip Enable	15	NC
5	CLR Clear	16	D0 Data Input
6	V _{CC}	17	D1 Data Input
7	A0 Digit Select	18	D2 Data Input
8	A1 Digit Select	19	D3 Data Input
9	WR Write	20	D4 Data Input
10	CU Cursor Select	21	D5 Data Input
11	CUE Cursor Enables	22	D6 Data Input

Maximum Ratings

Supply Voltage, V_{CC} -0.5 to +6.0 Vdc
 Voltage, Any Pin Respect to GND -0.5 to (V_{CC} +0.5) Vdc
 Operating Temperature -40°C to +85°C
 Storage Temperature -40°C to +100°C
 Relative Humidity (non condensing) @ 85°C 85%
 Maximum Solder Temperature, .063" (1.59mm) below Seating Plane, t<5 sec. 260°C

Optical Characteristics

Spectral Peak Wavelength 660 nm typ.
 Magnified Digit Size 0.225" X 0.192"
 Time Averaged Luminous Intensity (100% brightness, 0.5 mcd/digit min.
 8 Segments/Digit, V_{CC} = 5V 1.0 mcd/digit typ.
 LED to LED Intensity Matching 1.8:1.0 max.
 Device to Device Intensity Matching (one bin) 1.5:1.0 max.
 Bin to Bin Intensity Matching 1.9:1.0 max.
 Viewing Angle (off normal axis)
 Horizontal ±45°
 Vertical ±55°

DC CHARACTERISTICS

Parameter	-40°C			+25°C			+85°C			Units	Conditions
	Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.		
I _{CC} ⁽¹⁾ 4 Digits on 10 segments/digit		100	130		85	115		70	100	mA	V _{CC} = 5 V
I _{CC} Cursor ^(1,2)		140	170		120	150		100	130	mA	V _{CC} = 5 V
I _{CC} Blank ⁽¹⁾		2.0	5.0		1.5	4.0		1.0	2.7	mA	V _{CC} = 5 V, BL = 0.8 V
I _{IL} (all inputs)		80	180		60	160		45	90	µA	V _{IN} = 0.8 V, V _{CC} = 5 V
V _{IH}	2.7			2.7			2.7			V	V _{CC} = 5 V ± 0.5 V
V _{IL}			0.6			0.6			0.6	V	V _{CC} = 5 V ± 0.5 V

Notes: 1. Measured at 5 sec.
 2. 60 sec. maximum duration.

AC CHARACTERISTICS Guaranteed Minimum Timing Parameters @ $V_{CC}=4.5\text{ V} \leq V_{CC} \leq 5.5\text{ V}$

Parameter	Symbol	-40°C	+25°C	+85°C	Unit
Chip Enable Hold Time	T_{CES}	0	0	0	ns
Address Set Up Time	T_{AS}	10	10	10	ns
Cursor Set Up Time	T_{CUS}	10	10	10	ns
Chip Enable Hold Time	T_{CEH}	0	0	0	ns
Address Hold Time	T_{AH}	20	30	40	ns
Cursor Hold Time	T_{CUH}	20	30	40	ns
Clear Disable Time	T_{CLRD}	1	1	1	μs
Write Time	T_W	60	70	90	ns
Data Set Up Time	T_{DS}	20	30	50	ns
Data Hold Time	T_{DH}	20	30	40	ns
Clear Time ⁽³⁾	T_{CLR}	1	1	1	μs
Access Time ⁽²⁾	T_{ACC}	90	110	140	ns

Notes: 1. $V_{CC}=4.5$ is worst case. All timing parameters improve as V_{CC} increases.

2. Access time $T_{ACC}=T_{AS} + T_W + T_{DH}$.

3. T_{CLR} =time to clear ch. RAM, cursor RAM, counter RAM, counter chain, and the display.

4. T_{CLRD} =must be inactive before next write cycle.

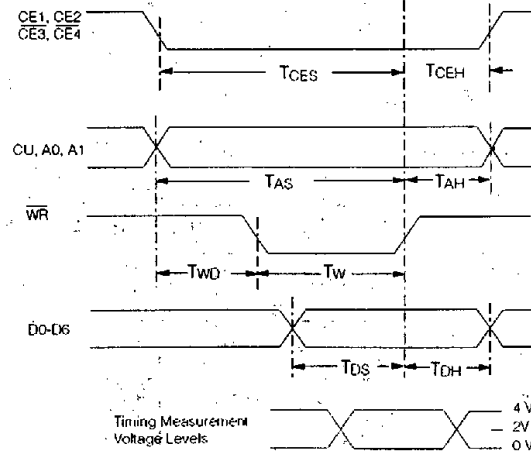
LOADING DATA

Setting the chip enable ($\overline{CE1}$, $\overline{CE2}$, $\overline{CE3}$, $\overline{CE4}$) to their true state will enable data loading. The desired data code (D0-D6) and digit address (A0, A1) must be held stable during the write cycle for storing new data.

Data entry may be asynchronous and random. (Digit 0 is defined as right hand digit with $A1 = A2 = 0$.)

To clear the entire internal four-digit memory, hold the clear (\overline{CLR}) low for one complete display multiplex cycle, 15 mS minimum. The clear function will clear both the ASCII RAM and the cursor RAM. Loading an illegal data code will display a blank.

**TIMING CHARACTERISTICS
WRITE CYCLE WAVEFORMS**



TYPICAL LOADING DATA STATE TABLE

\overline{BL}	$\overline{CE1}$	$\overline{CE2}$	$\overline{CE3}$	$\overline{CE4}$	CUE	CU	WR	\overline{CLR}	A1	A0	D6	D5	D4	D3	D2	D1	D0	Digit				
																		3	2	1	0	
H	X	X	X	X	L	X	H	H											G	R	E	Y
H	L	X	X	X	L	X	X	H	X	X	X	X	X	X	X	X	X	X	G	R	E	Y
H	X	L	X	X	L	X	X	H	X	X	X	X	X	X	X	X	X	X	G	R	E	Y
H	X	X	H	X	L	X	X	H	X	X	X	X	X	X	X	X	X	X	G	R	E	Y
H	X	X	X	H	L	X	X	H	X	X	X	X	X	X	X	X	X	X	G	R	E	Y
H	H	H	L	L	L	H	L	H	L	L	H	L	L	L	H	L	H	L	G	R	E	E
H	H	H	L	L	L	H	L	H	L	H	L	L	L	H	H	L	L	L	G	R	U	E
H	H	H	L	L	L	H	L	H	H	H	L	L	L	L	L	H	L	L	G	L	U	E
L	X	X	X	X	X	X	X	H	X	X									B	L	U	E
H	H	H	L	L	L	H	L	H	H	H	H	L	L	L	H	H	H	H	G	L	U	E
H	X	X	X	X	L	X	X	L														
H	H	H	L	L	L	H	L	H	X	X												

blank display

clears character display

see character code

see character set

LOADING CURSOR

Setting the chip enables ($\overline{CE1}$, $\overline{CE2}$, $\overline{CE3}$, $\overline{CE4}$) and cursor select (\overline{CU}) to their true state will enable cursor loading. A write (\overline{WR}) pulse will now store or remove a cursor into the digit location addressed by A0, A1, as defined in data entry. A cursor will be stored if $D0=1$ and will be removed if $D0=0$. Cursor will not be cleared by the \overline{CLR} signal. The cursor (\overline{CU}) pulse width should not be less than the write (\overline{WR}) pulse or erroneous data may appear in the display.

If the cursor is not needed, the cursor enable signal (\overline{CUE}) may be tied low to disable the display of the cursor function. Pulsing \overline{CUE} will give a flashing cursor. If the cursor has been loaded to any or all positions in the display, then \overline{CUE} will control whether the cursor(s) or the characters appear. \overline{CUE} does not affect the contents of cursor memory.

DISPLAY BLANKING

Blank the display by loading a blank or space into each digit of the display or by using the (\overline{BL}) display blank input.

Setting the (\overline{BL}) input low does not affect the contents of either data or cursor memory. A flashing display will result by pulsing (\overline{BL}). A flashing circuit can be constructed easily using a 555 astable multivibrator.

Figure 1 illustrates a circuit in which varying R1 (100K~10K) will have a flash rate of 1Hz~10Hz.

The display can be dimmed by pulsing the (\overline{BL}) at a frequency sufficiently fast to not interfere with the internal clock. This clock frequency may vary from 200 Hz to 1.3KHz. The dimming signal frequency should be 2.5KHz or higher. Dimming the display also reduces power consumption.

See Figure 2 for a simple dimming circuit using a 556. Adjusting potentiometer R2 will dim the display through frequency modulation (2.5 KHz to 4.4 KHz). Adjusting potentiometer R3 will dim the display by increasing the negative pulse width (10% to 50%).

FIGURE 1. FLASHING CIRCUIT FOR DL3416 USING A 555

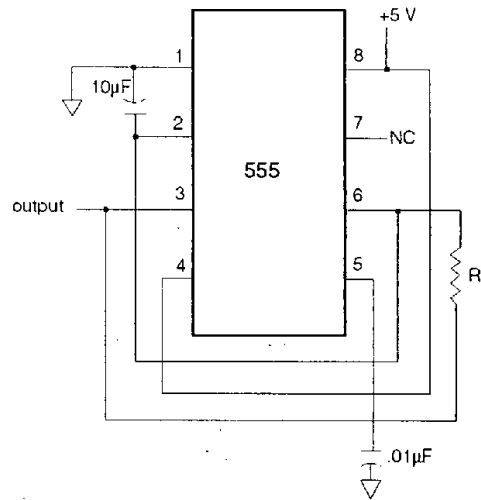
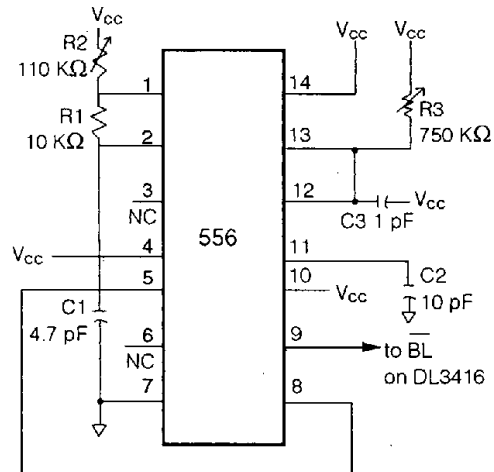


FIGURE 2. DIMMING CIRCUIT FOR DL3416 USING A 556



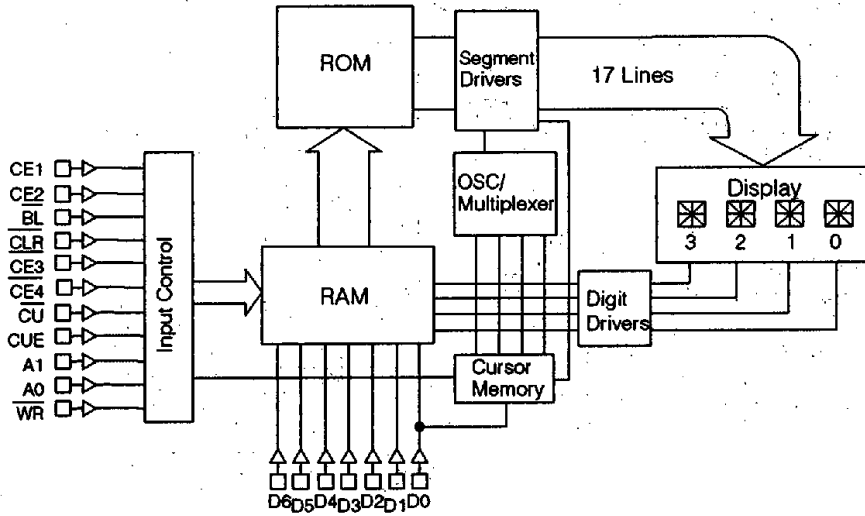
LOADING CURSOR STATE TABLE

\overline{BL}	$\overline{CE1}$	$\overline{CE2}$	$\overline{CE3}$	$\overline{CE4}$	\overline{CUE}	\overline{CU}	\overline{WR}	\overline{CLR}	A1	A0	D6	D5	D4	D3	D2	D1	D0	Digit			
																		3	2	1	0
H	X	X	X	X	L	X	H	H										B	E	A	R
H	X	X	X	X	H	X	H	H										B	E	A	R
H	H	H	L	L	H	L	L	H	L	L	X	X	X	X	X	X	H	B	E	■	■
H	H	H	L	L	H	L	L	H	H	L	X	X	X	X	X	X	H	B	■	■	■
H	H	H	L	L	H	L	L	H	H	H	X	X	X	X	X	X	H	■	■	■	■
H	H	H	L	L	H	L	L	H	H	L	X	X	X	X	X	L		■	E	■	■
H	X	X	X	X	L	X	H	H										B	E	A	R
H	H	H	L	L	L	L	L	H	H	H	X	X	X	X	X	L		B	E	A	R
H	X	X	X	X	H	X	H	H										B	E	■	■

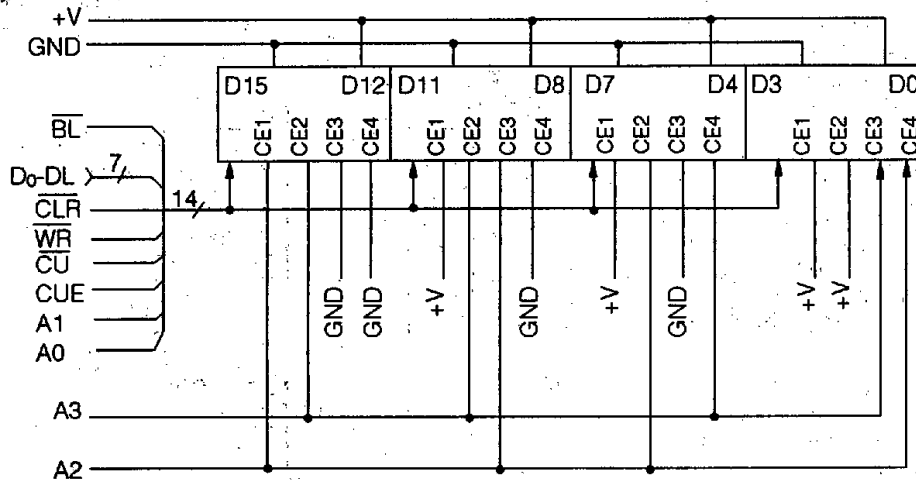
X = don't care

■ =

INTERNAL BLOCK DIAGRAM



TYPICAL SCHEMATIC FOR 16 DIGITS



CHARACTER SET

D6	D5	D4	hex	0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F
L	H	L	2		!	"	#	\$	%	&	'	<	>	*	+	,	-	.	/
L	H	H	3	0	1	2	3	4	5	6	7	8	9	[]	{	}	~	?
H	L	L	4	a	b	c	d	e	f	g	h	i	j	k	l	m	n	o	
H	L	H	5	p	q	r	s	t	u	v	w	x	y	z	[\]	^	_

All other input codes display "blank"

DESIGN CONSIDERATIONS

For details on design and applications of the DL3416 using standard bus configurations in multiple display systems, or parallel I/O devices, such as the 8255 with an 8080 or memory mapped addressing on processors such as the 8080, Z80, 6502, 8748, or 6800, refer to Appnote 14 and 20 in the current Siemens Optoelectronic Data Book.

ELECTRICAL & MECHANICAL CONSIDERATIONS

VOLTAGE TRANSIENT SUPPRESSION

We strongly recommend that the same power supply be used for the display and the components that interface with the display to avoid logic inputs higher than V_{CC} . Additionally, the LEDs may cause transients in the power supply line while they change display states. The common practice is to place .01 μ F capacitors close to the displays across V_{CC} and GND, one for each display, and one 10 μ F capacitor for every second display.

ESD PROTECTION

The metal gate CMOS IC of the DL3416 is extremely immune to ESD damage. However, users of these devices are encouraged to take all the standard precautions, normal for CMOS components. These include properly grounding personnel, tools, tables, and transport carriers that come in contact with unshielded parts. Where these conditions are not, or cannot be met, keep the leads of the device shorted together or the parts in anti-static packaging.

SOLDERING CONSIDERATIONS

THE DL3416 can be hand soldered with SN63 solder using a grounded iron set to 260°C.

Wave soldering is also possible following these conditions: Preheat that does not exceed 93°C on the solder side of the PC board or a package surface temperature of 85°C. Water soluble organic acid flux (except carboxylic acid) or resin-based RMA flux without alcohol can be used.

Wave temperature of 245°C \pm 5°C with a dwell between 1.5 sec. to 3.0 sec. Exposure to the wave should not exceed temperatures above 260°C for five seconds at 0.063" below the seating plane. The packages should not be immersed in the wave.

POST SOLDER CLEANING PROCEDURES

The least offensive cleaning solution is hot D.I. water (60°C) for less than 15 minutes. Addition of mild saponifiers is acceptable. Do not use commercial dishwasher detergents.

For faster cleaning, solvents may be used. Exercise care in choosing solvents as some may chemically attack the nylon package. Maximum exposure should not exceed two minutes at elevated temperatures. Acceptable solvents are TF (trichlorotrifluorethane), TA, 111 Trichloroethane, and unheated acetone.

Note: Acceptable commercial solvents are: Basic TF, Arklone P, Genesolve D, Blaco-tron TF, Freon TA, Genesolve DA, and Blaco-Iron TA.

Unacceptable solvents contain alcohol, methanol, methylene chloride, ethanol, TP35, TCM, TMC, TMS+, TE, or TES. Since many commercial mixtures exist, contact a solvent vendor for chemical composition information.

Some major solvent manufacturers are: Allied Chemical Corporation, Specialty Chemical Division, Morristown, NJ; Baron-Blakeslee, Chicago, IL; Dow Chemical, Midland, MI; E.I. DuPont de Nemours & Co., Wilmington, DE.

For further information refer to Appnotes 18 and 19 in the current Siemens Optoelectronic Data Book.

An alternative to soldering and cleaning the display modules is to use sockets. Eighteen pin DIP sockets .600" wide with .100" centers work well for single displays. Multiple display assemblies are best handled by longer SIP sockets or DIP sockets when available for uniform package alignment. Socket manufacturers are Aries Electronics, Inc., Frenchtown, NJ; Garry Manufacturing, New Brunswick, NJ; Robinson-Nugent, New Albany, IN; and Samtec Electronic Hardware, New Albany, IN.

For further information refer to Appnote 22 in the current Siemens Optoelectronic Data Book.

OPTICAL CONSIDERATIONS

The .225" high characters of the DL3416 gives readability up to eight feet. The user can build a display that enhances readability over this distance by proper filter selection.

Using filters emphasizes the contrast ratio between a lit LED and the character background. This will increase the discrimination of different characters. The only limitation is cost. Remember to take into consideration the ambient lighting environment for the best cost/benefit ratio for filters.

Incandescent (with almost no green) or fluorescent (with almost no red) lights do not have the flat spectral response of sunlight. Plastic band-pass filters are an inexpensive and effective way to strengthen contrast ratios. The DL3416 is a standard red display and should be matched with long wavelength pass filter in the 600 nm to 620 nm range. For displays of multiple colors, neutral density grey filters offer the best compromise.

Additional contrast enhancement can be gained by shading the displays. Plastic band-pass filters with built-in louvers offer the next step up in contrast improvement. Plastic filters can be improved further with anti-reflective coatings to reduce glare. The trade-off is fuzzy characters. Mounting the filters close to the display reduces this effect. Take care not to overheat the plastic filter by allowing for proper air flow.

Optimal filter enhancements are gained by using circular polarized, anti-reflective, band-pass filters. The circular polarizing further enhances contrast by reducing the light that travels through the filter and reflects back off the display to less than 1%.

Several filter manufacturers supply quality filter materials. Some of them are: Panelgraphic Corporation, W. Caldwell, NJ; SGL Homalite, Wilmington, DE; 3M Company, Visual Products Division, St. Paul, MN; Polaroid Corporation, Polarizer Division, Cambridge, MA; Marks Polarized Corporation, Deer Park, NY; Hoya Optics, Inc., Fremont, CA.

One last note on mounting filters: recessing displays and bezel assemblies is an inexpensive way to provide a shading effect in overhead lighting situations. Several bezel manufacturers are: R.M.F. Products, Batavia, IL; Nobex Components, Griffith Plastic Corp., Burlingame, CA; Photo Chemical Products of California, Santa Monica, CA; I.E.E.-Atlas, Van Nuys, CA.

Refer to Siemens Appnote 23 for further information.